



SKYTEC BOLT

The metal bonded diamond grinding tool
for the PowerGrind process

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The new SKYTEC BOLT type of metal bond was specially developed for the patented Agathon PowerGrind process. Electrical discharge conditioning enables the grinding wheel to be continuously and simultaneously dressed, sharpened and cleaned during the grinding process. The maximum chip space and the permanent free-cutting wheel topography of the SKYTEC BOLT enable the tool inserts to be processed with the greatest economic efficiency.

+ Shorter grinding time

Specially adapted diamond grains and the newly developed metal bond enable the contact time to be reduced by up to 50 percent in combination with the PowerGrind process.

+ Low grinding forces

The individually adapted specification for the grinding wheel and ongoing conditioning reduces the grinding force.

+ Minimal chipping

The use of small grain sizes leads to a significant reduction in cutting edge chipping with a constant level of economic efficiency.



Application

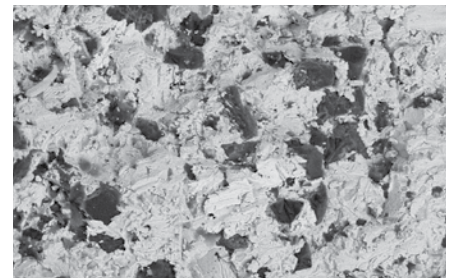
Grinding of cemented carbide, cermet and PCBN inserts



Foto: AGATHON AG

Comparison of grinding layer

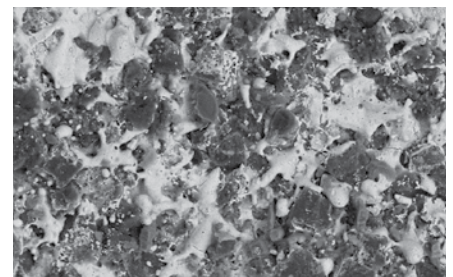
Conditioning with an SiC or aluminium oxide wheel



20 µm grain bond

- Low grain protrusion
- Diamond is fractured and mechanically affected

Conditioning using the PowerGrind process



20 µm grain bond

- High grain protrusion
- Low diamond break-out and small bonding surfaces

Product range

Diameter	Width of the abrasive layer	Height of the abrasive layer	Specification	Machine type
400	8, 10, 12, 14 16, 18, 20	6	Depending on the application	Agathon Combi & Penta with PowerGrind